### 700V N-Channel MOSFET

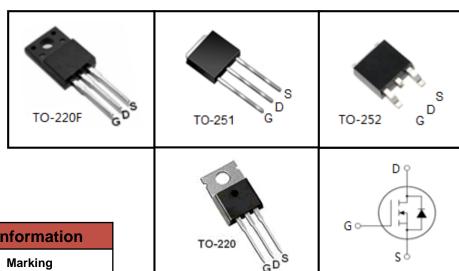
#### **FEATURES**

- Fast switching
- 100% avalanche tested
- Improved dv/dt capability

#### **APPLICATIONS**

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Power Factor Correction (PFC)

Device Marking and Package Information					
Device	Package	Marking			
CS5N70F	TO-220F	CS5N70F			
CS5N70P	TO-220	CS5N70P			
CS5N70U	TO-251	CS5N70U			
CS5N70D	TO-252	CS5N70D			



<b>Absolute Maximum Ratings</b> $T_C = 25^{\circ}C$ , unless otherwise noted						
Davameter	Symbol		I I m it			
Parameter	Symbol	TO-220F	TO-252	TO-251	TO-220	Unit
Drain-Source Voltage (V <sub>GS</sub> = 0V)	V <sub>DSS</sub>	700			٧	
Continuous Drain Current	I <sub>D</sub>	5			А	
Pulsed Drain Current (note1)	I <sub>DM</sub>	20			Α	
Gate-Source Voltage	V <sub>GSS</sub>	±30		V		
Single Pulse Avalanche Energy (note2)	E <sub>AS</sub>	88			mJ	
Avalanche Current (note1)	I <sub>AR</sub>	4.2			А	
Repetitive Avalanche Energy (note1)	E <sub>AR</sub>	35			mJ	
Power Dissipation (T <sub>C</sub> = 25°C)	P <sub>D</sub>	54		83		W
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55~+150			°C	

Thermal Resistance						
Baranatar	Symbol	Value				11
Parameter		TO-220F	TO-252	TO-251	TO-220	Unit
Thermal Resistance, Junction-to-Case	R <sub>thJC</sub>	2.3		1.5		00.004
Thermal Resistance, Junction-to-Ambient	R <sub>thJA</sub>	62.5	60		°C/W	



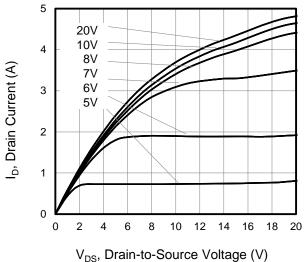
Parameter		rwise noted				
	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_{D} = 250\mu A$	700			V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = 700 \text{V}, V_{GS} = 0 \text{V}, T_{J} = 25^{\circ}\text{C}$			1	μΑ
Gate-Source Leakage	I <sub>GSS</sub>	$V_{GS} = \pm 30V$			±100	nA
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	3.0		4.0	V
Drain-Source On-Resistance (Note3)	R <sub>DS(on)</sub>	$V_{GS} = 10V, I_{D} = 2.5A$		1.9	2.4	Ω
Dynamic						
Input Capacitance	C <sub>iss</sub>	V 0V		700		pF
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0V,$ $V_{DS} = 25V,$		94		
Reverse Transfer Capacitance	C <sub>rss</sub>	f = 1.0MHz		12		
Total Gate Charge	$Q_g$			19		
Gate-Source Charge	$Q_gs$	$V_{DD} = 560V, I_{D} = 5A,$ $V_{GS} = 10V$		3.7		nC
Gate-Drain Charge	$Q_{gd}$	VGS = 10 V		11		
Turn-on Delay Time	t <sub>d(on)</sub>			13		
Turn-on Rise Time	t <sub>r</sub>	$V_{DD} = 350V, I_{D} = 5A,$		20		
Turn-off Delay Time	t <sub>d(off)</sub>	$R_G = 25 \Omega$		76		ns
Turn-off Fall Time	t <sub>f</sub>			40		
Drain-Source Body Diode Character	istics					
Continuous Body Diode Current	I <sub>s</sub>	T 05.00			5	
Pulsed Diode Forward Current	I <sub>SM</sub>	T <sub>C</sub> = 25 °C			20	A
Body Diode Voltage	V <sub>SD</sub>	$T_J = 25^{\circ}\text{C}, I_{SD} = 2.5\text{A}, V_{GS} = 0\text{V}$			1.4	V
Reverse Recovery Time	t <sub>rr</sub>	$V_{GS} = 0V, I_{S} = 5A,$		260		ns
Reverse Recovery Charge	Q <sub>rr</sub>	$di_{F}/dt = 100A / \mu s$		3.8		μC

#### **Notes**

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature
- 2. L=10mH,  $V_{DD}$  = 50V,  $R_G$  = 25  $\Omega$ , Starting  $T_J$  = 25  $^{\circ}C$
- 3. Pulse Test: Pulse width ≤ 300µs, Duty Cycle ≤ 1%

### **Typical Characteristics** $T_J = 25^{\circ}\text{C}$ , unless otherwise noted

Figure 1. Output Characteristics ( $T_J = 25^{\circ}C$ )



ls, Source Current (A)

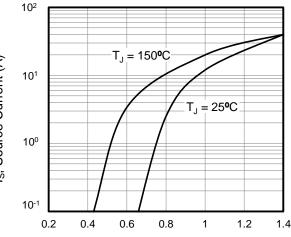


Figure 2. Body Diode Forward Voltage

V<sub>SD</sub>, Source-to-Drain Voltage (V)

Figure 3. Drain Current vs. Temperature

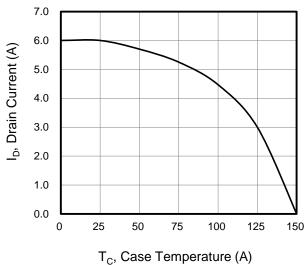
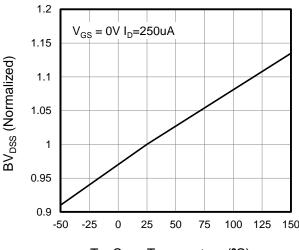


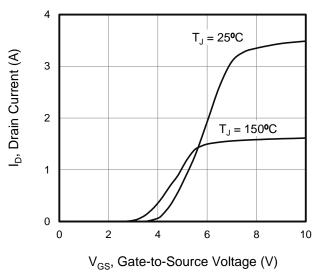
Figure 4. BV<sub>DSS</sub> Variation vs. Temperature



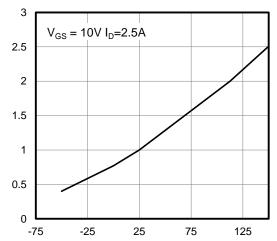
T<sub>C</sub>, Case Temperature (°C)

Figure 6. On-Resistance vs. Temperature

Figure 5. Transfer Characteristics



R<sub>DS(on)</sub>, On-Resistance (Normalized)



T<sub>J</sub>, Junction Temperature (°C)

### **Typical Characteristics** $T_J = 25^{\circ}\text{C}$ , unless otherwise noted

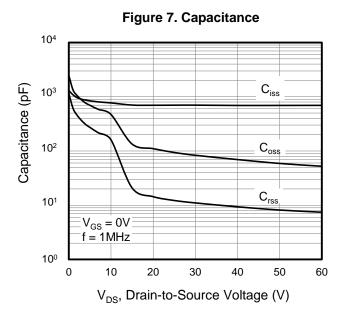


Figure 9. Transient Thermal Impedance TO-262,TO-251,TO-252

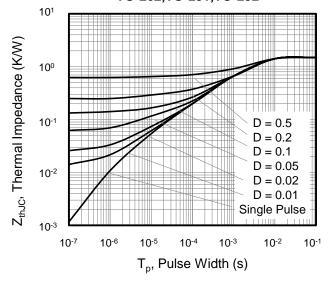


Figure 8. Gate Charge

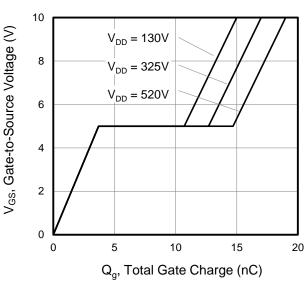


Figure 10. Transient Thermal Impedance
TO-220F

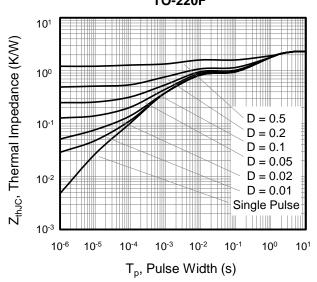


Figure A: Gate Charge Test Circuit and Waveform

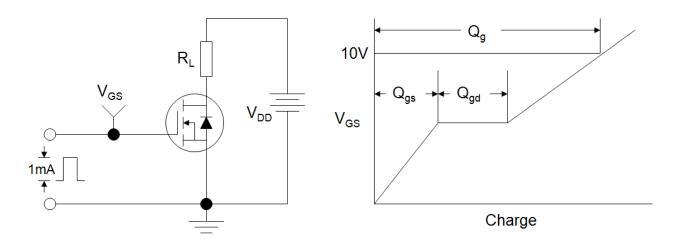


Figure B: Resistive Switching Test Circuit and Waveform

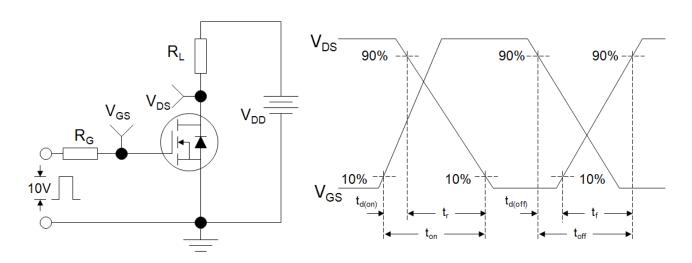
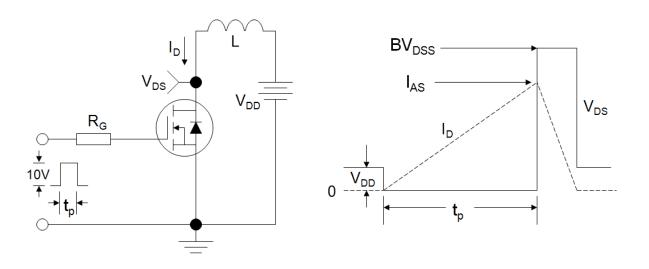
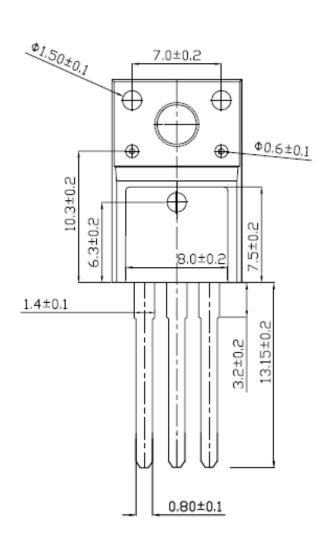
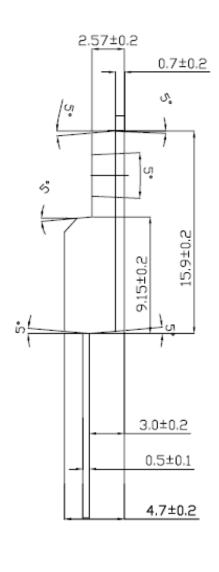


Figure C: Unclamped Inductive Switching Test Circuit and Waveform

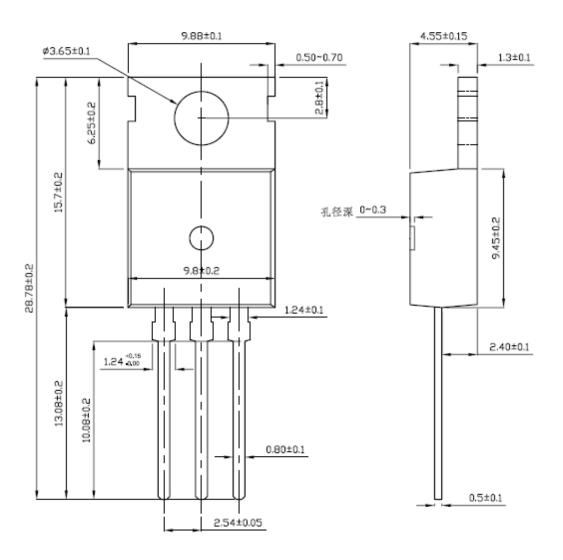


### **TO-220F**

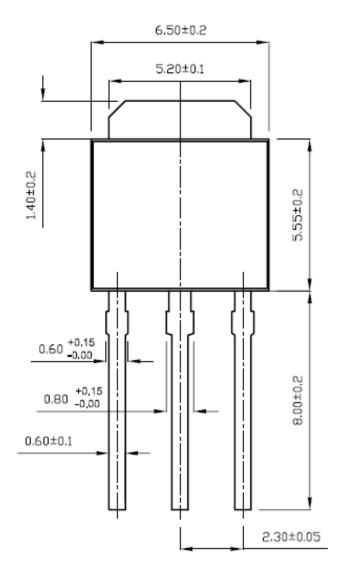


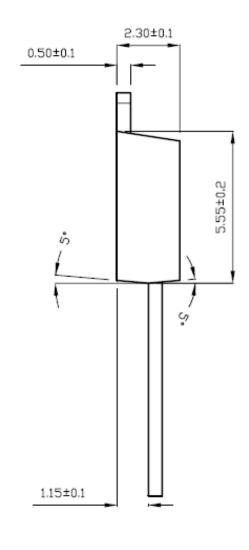


**TO-220** 

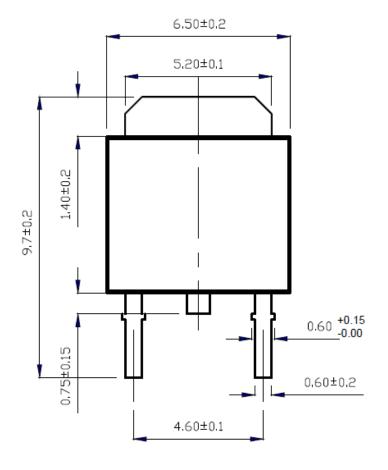


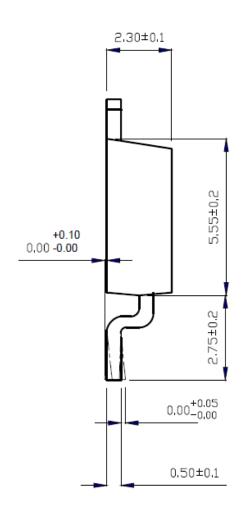
TO-251





**TO-252** 







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